

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S22	6	S15 and S21	US-PGPU B; USPAT; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/30 08:20
S26	11206	S13 or S21	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/30 08:30
S27	46	S26 and (bump or bump\$3 or solder\$3 or bond\$3) and ((wafer or semiconductor or chip) near5 ((transfer or storage or magazine or cabinet or drawer or shelf) adj (device or apparatus or system or tool)))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/11/07 18:34
S28	19	S26 and ((control\$4 near5 program)near5 (((pre or preliminary or post or final or subsequent) near5 heat\$3) or preheat\$3 or (pre adj heat\$3)or (post adj heat\$3) or anneal\$3 or temperature))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/30 16:12

## EAST Search History

S29	754	S26 and (control\$4 near5 (((pre or preliminary or post or final or subsequent) near5 heat\$3) or preheat\$3 or (pre adj heat\$3)or (post adj heat\$3) or anneal\$3 or temperature))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2006/10/30 09:01
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